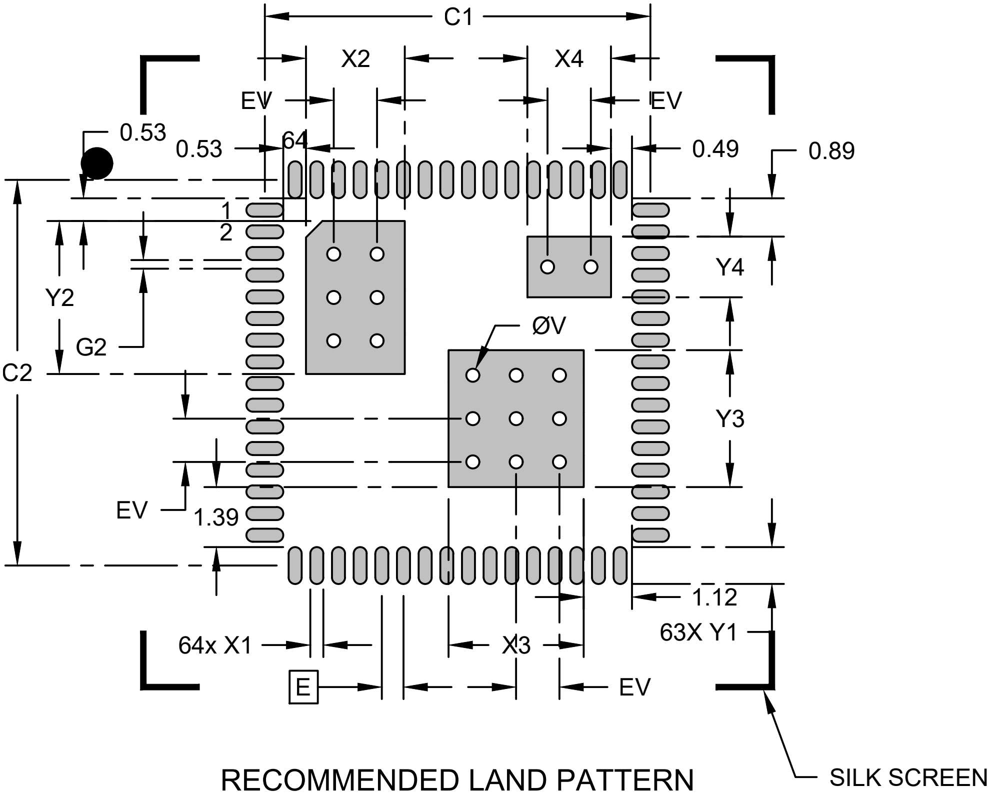
64-Lead Very-Thin Grid-Array Quad Flatpack No-Lead Package (8QW) - 9x9x0.927 mm Body [VGQFN] with 3 Exposed Pads and Stepped Wettable Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.85
Contact Pad to Contact Pad (X60)	G2	0.20		
Thermal Via Diameter	V		1.00	
Thermal Via Pitch	EV		0.30	

Units		MM
Dimension Limits		MAX
Center Pad 1 Width	X2	2.28
Center Pad 1 Length	Y2	3.53
Center Pad 2 Width	X3	3.12
Center Pad 2 Length	Y3	3.16
Center Pad 3 Width	X4	1.93
Center Pad 3 Length	Y4	1.40

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.

2. For best soldering results, please refer to the current industry standard IPC-7093.